

# IR WAFER2



大量科技  
TA LIANG



## FEATURE

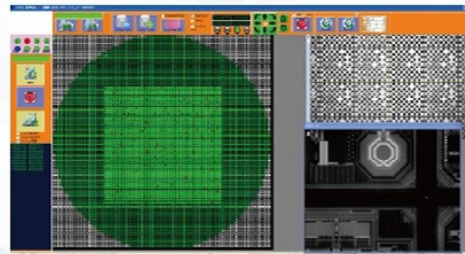
Wafer Size 12" & 8"

UPH 500EA/hrs (3 x 3 mm)

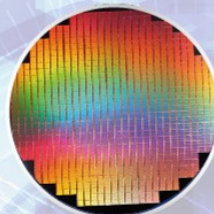
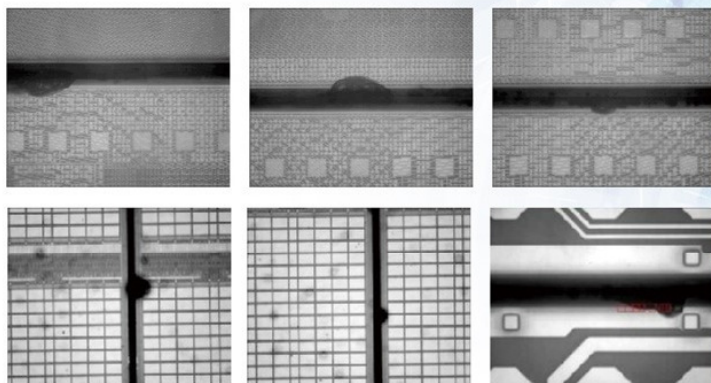
Dimension 2850mm(W) x 1760mm(L) x 2500mm(H)

Software Feature Auto Alignment & Auto Correction Die  
Output Auto-Merge Map File  
Edge / Sidewall Chipping Inspection  
Software Auto Focus

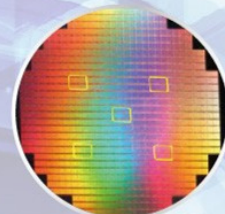
Machine Feature Auto Loader and Unloader  
X, Y, Z,  $\theta$  4-Axis Stage  
Air Shockproof Mechanism  
Auto Barcode Reader  
Marble Base and Translation Stage



*IR Water Inspection system  
Finish inspection report*



*Full area Inspection*



*Specify the location  
(Any Area)*